



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-10-30
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SM30T21CAY	AHZH*TYB021M	A	64BA	2018-10-30
Amount	UoM	Unit type	ST ECOPACK Grade	
250.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	6.69-5.63-2.38	2	J bend	
Comment	SMC CLIP (SOD 15)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.87	Die - Leadframe	3460
Lead	6.96	Soft solder	27832

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	6.958	Soft solder	27832
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	6.958	Soft solder	920249

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	AHZH*TY8021M					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	9.345	mg	supplier	die	Silicon (Si)	7440-21-3		9.059	mg	969395	36236
				supplier	metallization	Aluminium (Al)	7429-90-5		0.053	mg	5673	212
				supplier	metallization	Gold (Au)	7440-57-5		0.038	mg	4066	152
				supplier	metallization	Nickel (Ni)	7440-02-0		0.038	mg	4066	152
				supplier	Passivation	Silicon Oxide	7631-86-9		0.052	mg	5564	208
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.035	mg	3745	140
				supplier	back side metallization	Gold (Au)	7440-57-5		0.012	mg	1284	48
Leadframe	M-004 Copper and its alloys	79.541	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.058	mg	6207	232
				supplier	alloy	Copper (Cu)	7440-50-8		78.660	mg	989037	314676
				supplier	alloy	Iron (Fe)	7439-89-6		0.079	mg	993	316
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.024	mg	302	96
				supplier	metallization	Nickel (Ni)	7440-02-0		0.769	mg	9668	3076
Soft solder	Solder	7.561	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	6.958	mg	920249	27832
				supplier	solder	Silver (Ag)	7440-22-4		0.188	mg	24864	752
				supplier	solder	Tin (Sn)	7440-31-5		0.377	mg	49861	1508
				supplier	solder	flux residue	Proprietary		0.038	mg	5026	152
				supplier	mold compound	Amorphous Silica	7631-86-9		81.920	mg	730991	327680
Encapsulation	M-011 Other inorganic materials	112.067	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		21.293	mg	190002	85172
				supplier	mold compound	Phenol resin	9003-35-4		3.362	mg	30000	13448
				supplier	mold compound	Bisphenol A-bisphenol A diglycidyle ether poly	25036-25-3		3.362	mg	30000	13448
				supplier	mold compound	Carbon black	1333-86-4		1.009	mg	9004	4036
				supplier	mold compound	Triphenylphosphine	603-35-0		0.785	mg	7005	3140
connections coating	Solder	1.972	mg	supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.336	mg	2998	1344
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.972	mg	1000000	7888
Clip	M-004 Copper and its alloys	39.514	mg	supplier	alloy	Copper (Cu)	7440-50-8		39.514	mg	1000000	158056